



VDRM

T(AV)

Iтsм dV/dt\*

dl/dt

**KEY PARAMETERS** 

4200V

4810A

60000A

2000V/µs

500A/µs

\* Higher dV/dt selections are available on request

# DCR4880M42

#### Replaces DS5943-8

Phase Control Thyristor

DS5943-9	March 2022	(LN41629)

### FEATURES

- Double Side Cooling
- High Surge Capability

#### **APPLICATIONS**

- Crowbar
- High Power Drives
- High Voltage Power Supplies
- Static Switches

### **VOLTAGE RATINGS**

Part and Ordering Number	Repetitive Peak Voltages VDRM and VRRM (V)	Conditions
DCR4880M42* DCR4880M40 DCR4880M35	4200 4000 3500	$T_{vj} = -40^{\circ}$ C to 125°C, IDRM = IRRM = 300mA, VDRM, VRRM tp = 10ms VDSM & VRSM = VDRM & VRRM + 100V respectively

Lower voltage grades available.

\*4100V @ -40°C, 4200V @ 0°C

#### **ORDERING INFORMATION**

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

#### DCR4880M42

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

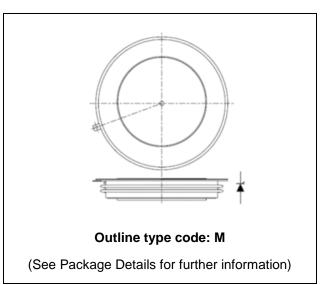


Fig. 1 Package outline

# **CURRENT RATINGS**

T<sub>case</sub> = 60°C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Si	de Cooled			
Ιτ(Αν)	Mean on-state current	Half wave resistive load	4810	А
It(rms)	RMS value	-	7560	А
Іт	Continuous (direct) on-state current	-	6930	А

### SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
Ітѕм	Surge (non-repetitive) on-state current	10ms half sine, Tcase = 125°C	60.0	kA
l²t	I <sup>2</sup> t for fusing	VR = 0	18.0	MA <sup>2</sup> s

# THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
	Rth(j-c) Thermal resistance - junction to case	Double side cooled	DC	-	5.2	°C/kW
Rth(j-c)		Single side cooled	Anode DC	-	10.1	°C/kW
			Cathode DC	-	10.8	°C/kW
Balan	Thermal registeres access to heateink	Clamping force 83kN (with mounting compound)	Double side	-	1.0	°C/kW
Rth(c-h)	h) Thermal resistance - case to heatsink		Single side	-	2.0	°C/kW
Tvj	Virtual junction temperature	Blocking Vdrm / Vrrm		-	125	°C
Tstg	Storage temperature range			-55	125	°C
Fm	Clamping force			74	91	kN

# **DYNAMIC CHARACTERISTICS**

Symbol	Parameter	Test Conditior	IS	Тур.	Max.	Units
1	Deals assess and aff state assess	At VRRM/VDRM, Tcase = 125°C		-	300	mA
Irrm/Idrm	Peak reverse and off-state current	At 50% VRRM/VDRM, Tcase = 7	125°C	20	-	mA
Symbol	Parameter	Test Conditions		Min.	Max.	Units
Vтм	Instantaneous forward voltage	At 4000A peak, Tj = 125°C		1.30	1.45	V
dV/dt	Max. linear rate of rise of off-state voltage	То 67% Vdrm, Tj = 125°C, g	ate open	-	2000	V/µs
dl/dt	Rate of rise of on-state current	From 67% VDRM to 2x IT(AV) Gate source 30V, $10\Omega$	Repetitive 50Hz	-	200	A/µs
anat		tr < 0.5µs, Tj = 125°C	Non-repetitive	-	500	A/µs
N	Threshold voltage - Low level	500A to 3400A at Tcase = 1	25°C	-	0.81	V
<b>V</b> τ(το)	Threshold voltage - High level	3400A to 9000A at Tcase = 1	25°C	-	0.98	V
-	On-state slope resistance - Low level	500A to 3400A at Tcase = 1	25°C	-	0.17	mΩ
ľτ	On-state slope resistance - High level	3400A to 9000A at Tcase = 1	25°C	-	0.12	mΩ
tgd	Delay time	Vb = 67% Vbrm, gate source tr = 0.5µs, Tj = 25°C	e 30V, 10Ω	-	3	μs
tq	Turn-off time	IT = 5000A, Tj = 125°C, VR = dI/dt = 5A/µs, dVɒr/dt = 20\		-	900	μs
Qs	Stored charge	I⊤ = 1700A, Tj = 125°C, dl/di	: = 1A/μs	2570	5350	μC
IRR	Reverse recovery current	Vr ~ 1700V, Cs = 1μF, Rs = 63Ω		42	68	А
IL.	Latching current	Tj = 25°C, V <sub>D</sub> = 5V		-	3	А
Ін	Holding current	Тј = 25°С, R <sub>G-</sub> к = ∞, Iтм = 50	0A, I⊤ = 5A	-	300	mA

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# GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
Vgт	Gate trigger voltage	Vdrm = 5V, Tcase = 25°C	1.5	V
Vgd	Gate non-trigger voltage	At 50% VDRM, Tcase = 125°C	0.4	V
Ідт	Gate trigger current	VDRM = 5V, Tcase = 25°C	400	mA
Igd	Gate non-trigger current	At 50% Vdrm, Tcase = 125°C	10	mA

# CURVES

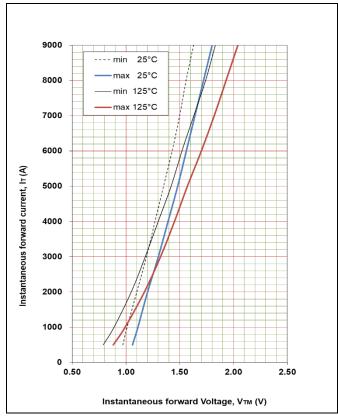


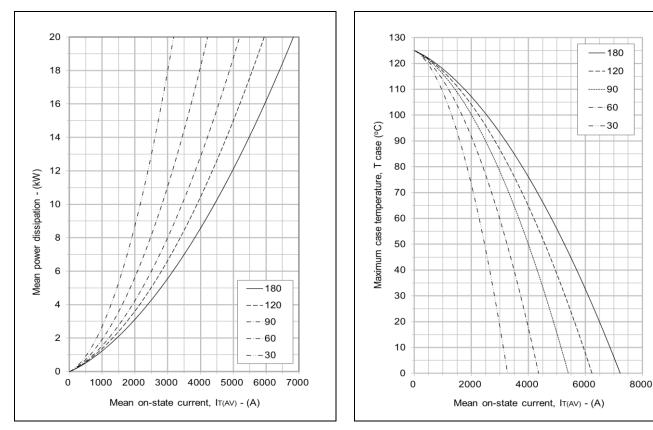
Fig. 2 Maximum & minimum on-state characteristics

# **VTM EQUATION**

 $V_{TM} = A + B.ln(I_T) + C.I_T + D.\sqrt{I_T}$ 

Where A = 0.090451B = 0.121408C = 0.000109D = -0.001368These values are valid for T<sub>j</sub> =  $125^{\circ}$ C for I<sub>T</sub> 500A to 9000A

# DCR4880M42



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Fig. 3 On-state power dissipation - sine wave

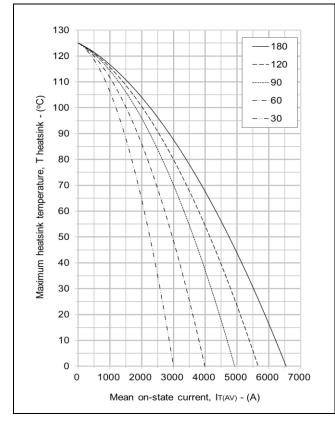


Fig. 5 Maximum permissible heatsink temperature, double side cooled - sine wave

Fig. 4 Maximum permissible case temperature, double side cooled - sine wave

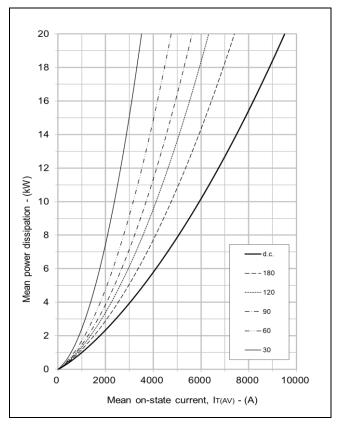


Fig. 6 On-state power dissipation - rectangular wave

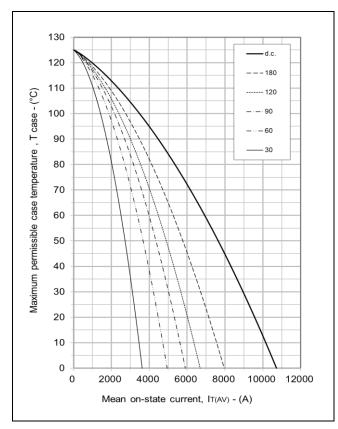
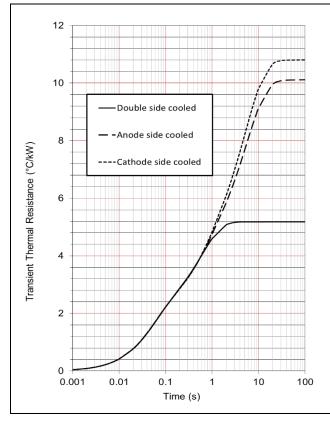


Fig. 7 Maximum permissible case temperature, double side cooled - rectangular wave



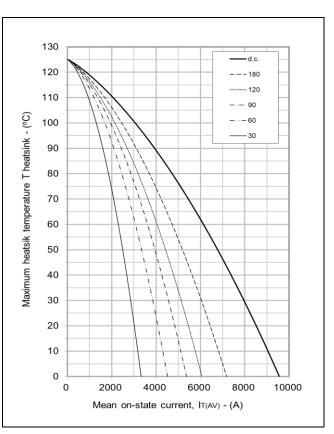


Fig. 8 Maximum permissible heatsink temperature, double side cooled - rectangular wave

		1	2	3	4
Double side	Ri(°C/kW)	1.995	1.243	1.945	0.005
cooled	Ti(s)	0.050	0.593	0.592	110.511
Anode side	Ri(°C/kW)	6.093	1.957	2.042	0.036
cooled	Ti(s)	5.460	0.511	0.050	110.174
Cathode side	Ri(°C/kW)	6.857	1.876	2.063	0.025
cooled	Ti(s)	5.181	0.557	0.050	110.155

$$Z_{th} = \sum_{i=1}^{i=4} R_i \cdot \left(1 - \exp\left(-\frac{T}{T_i}\right)\right)$$

 $\Delta R_{th(j-c)}$  Conduction

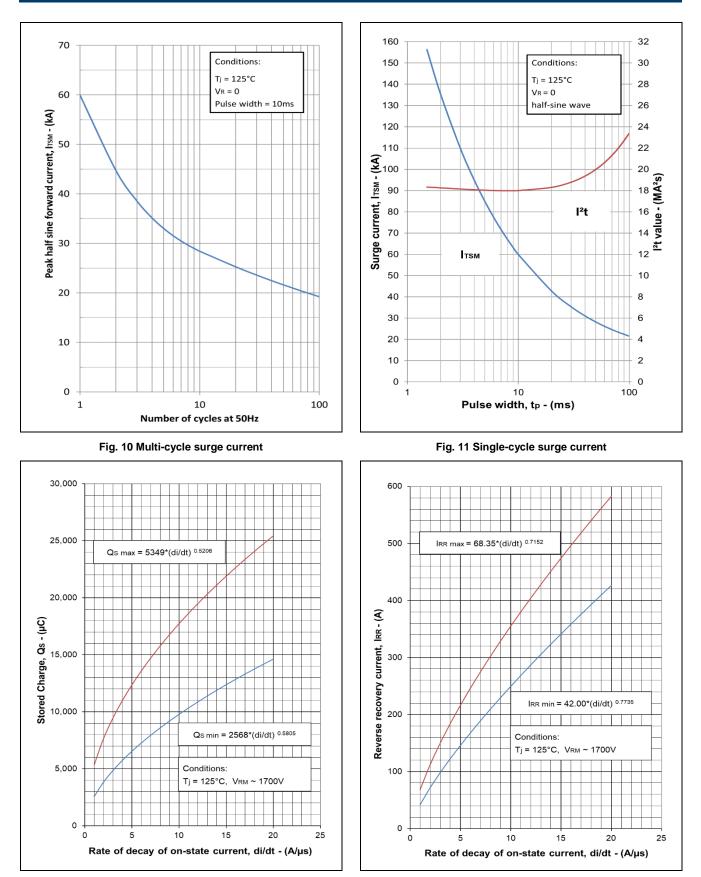
Tables show the increments of thermal resistance R  $_{\text{frij-ej}}$  when the device operates at conduction angles other than d.c.

Cathode Sided Cooling		
(Z)		
rect.		
0.36		
0.50		
0.57		
0.64		
0.71		
0.75		



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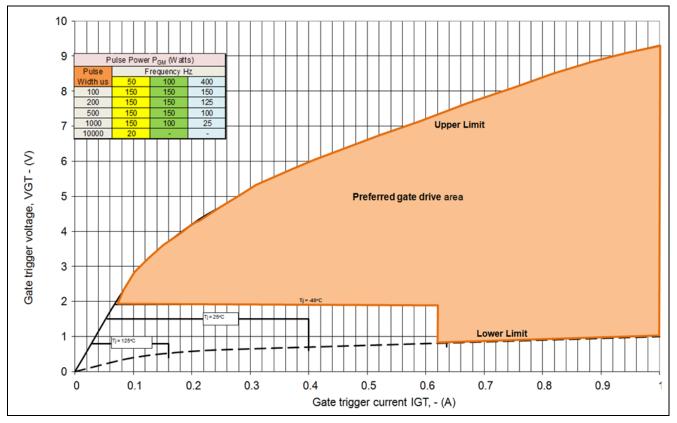
# DCR4880M42



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Fig. 12 Stored charge

Fig. 13 Reverse recovery current



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Fig.14 Gate characteristics

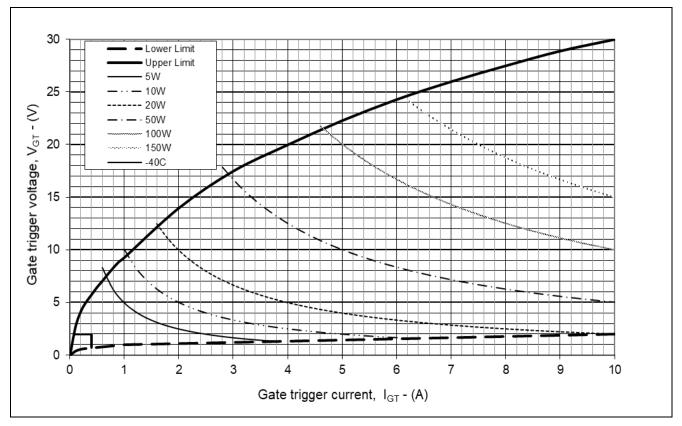


Fig. 15 Gate characteristics

Maximum

Thickness

(mm)

26.8

26.8

26.5

26.5

26.3

26.3

26.1

26.1

25.9

Minimum

Thickness

(mm)

26.3

26.3

26.0

26.0

25.7

25.7

25.6

25.6

25.4

### **PACKAGE DETAILS**

For further package information, please contact Customer services.

All dimensions in mm, unless stated otherwise.

DO NOT SCALE

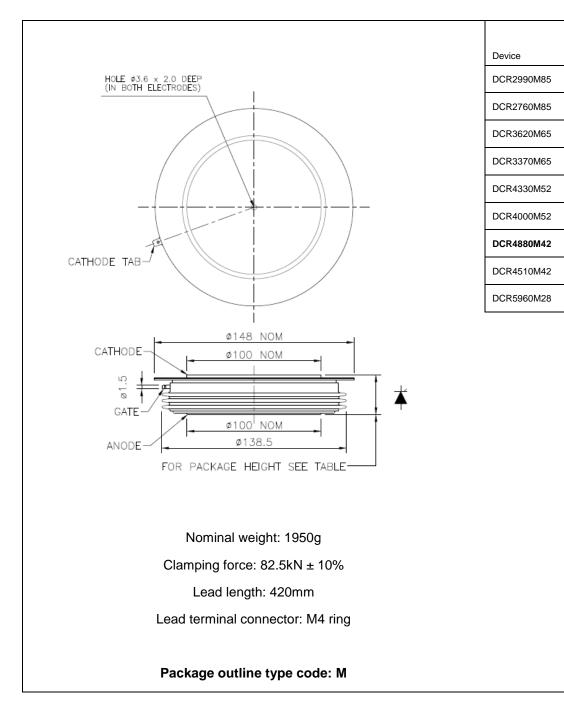


Fig. 16 Package outline

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